

IN THE CLAIMS:

1. (Previously Presented) A chip carrier comprising:
a base;
an inner well extending along a length of a periphery of the base; and
an outer well extending along a length of a periphery of the inner well.
2. (Original) The chip carrier according to claim wherein the first well and the second well form a flexible structure.
3. (Original) The chip carrier according to claim 1 wherein the outer well includes an outer wall and an inner wall and the inner well includes an outer wall coupled to the inner wall of the outer well.
4. (Previously Presented) The chip carrier according to claim 1 wherein the base includes an upper surface and wherein the outer well has a first base and the inner well has a second base wherein there is a first distance between the first base and the upper surface and there is a second distance between the second base and the upper surface, the first distance greater than the second distance.
5. (Previously Presented) The chip carrier according to claim 1 further comprising an integrated circuit removably positioned on the base.

6. (Previously Presented) The chip carrier according to claim 1 wherein the outer well and the inner well encircle the base.

7. (Previously Presented) The chip carrier according to claim 1 wherein at least one of the outer well and the inner well encircle the base.

Claim 8-20 (Canceled)

21. (Previously Presented) The chip carrier according to claim 1 further comprising:

an upper surface;
an integrated circuit positioned on the base and below the upper surface, the integrated circuit having leads;
wherein the inner well has a base, the leads positioned above the base and below the upper surface.

22. (Previously Presented) The chip carrier according to claim 1 wherein the base, the inner well, and the outer well form an integrated circuit carrier and the chip carrier further comprises a plurality of integrated circuit carriers.

23. (Previously Presented) The chip carrier according to claim 1 further comprising

a cover adapted to hold an integrated circuit in the chip carrier.

24. (Previously Presented) The chip carrier according to claim 1 further comprising a cover for holding an integrated circuit in the chip carrier.

25. (Previously Presented) A chip carrier comprising:
a base;
an inner well extending along a length of a periphery of the base; and
an outer well extending along a length of a periphery of the inner well,
the chip carrier adapted to temporarily hold an integrated circuit in the chip carrier.

26. (Previously Presented) The chip carrier according to claim 25 wherein the base, the inner well, and the outer well form an integrated circuit carrier and the chip carrier further comprises a plurality of integrated circuit carriers.

27. (Previously Presented) The chip carrier according to claim 25 further comprising a cover adapted to hold an integrated circuit in the chip carrier.

28. (Previously Presented) The chip carrier according to claim 25 further comprising a cover for holding an integrated circuit in the chip carrier.

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